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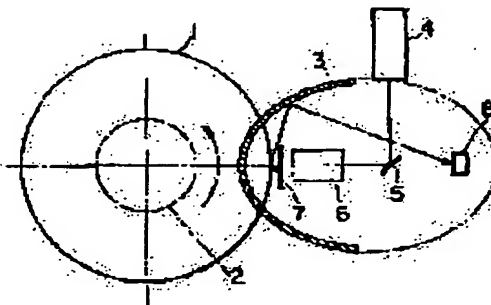
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(54) METHOD AND DEVICE FOR EXAMINING END PART DEFECT

(57)Abstract:

PROBLEM TO BE SOLVED: To distinguish crack, chip and flaw and examine the properties such as surface roughness of the end face of a semiconductor wafer easily, without the aid of manpower and with a simple device.

SOLUTION: In a device, of the diffracted lights produced by irradiating the gathered parallel lights on first end part of the object under examination in the proximity of the first focus of an elliptical mirror 3, diffracted light of lower order is intercepted by a light-intercepting plate 7, diffracted light of higher order is gathered by lice elliptical mirror 3, and the components of the diffracted light of higher order are analyzed and classified by a detector placed at the second focus of the elliptic mirror. It is thus possible to distinguish crack, chip and flaw and automatically classify surface roughness too even with the aid of a simple optical examination device.



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